

N-Ch MOSFET

General Description

The WSF15N10G uses advanced SGTMOS technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics. This device is specially designed to get better ruggedness and suitable to use in Synchronous rectification applications

Features

- advanced SGTMOS technology
- Low gate charge
- Low R_{DS(ON)}

Product Summery

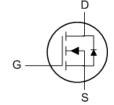
| BVDSS | RDSON | ID | | |
|-------|-------|-----|--|--|
| 100V | 75mΩ | 15A | | |

Applications

- Fast Switching
- DC-DC Power System
- Load Switch

TO-252 Pin Configuration





Absolute Maximum Ratings at Tj=25℃ unless otherwise noted

| Symbol | Parameter | Rating | Units | |
|-----------------------|---|------------|-------|--|
| V_{DS} | Drain-Source Voltage | 100 | V | |
| V_{GS} | Gate-Source Voltage | ±20 | V | |
| I _D | Continuous Drain Current1) | 15 | Α | |
| I _{D, pulse} | Pulsed Drain Current ²⁾ | 45 | Α | |
| E _{AS} | Single Pulse Avalanche Energy ⁴⁾ | 5.5 | mJ | |
| P _D | Total Power Dissipation ³⁾ | 36 | W | |
| T _{STG} | Storage Temperature Range | -55 to 150 | ℃ | |
| TJ | Operating Junction Temperature Range | -55 to 150 | ℃ | |

Thermal Data

| Symbol | Parameter | Тур. | Max. | Unit |
|-------------------|--|------|------|------|
| R _{0JA} | Thermal Resistance Junction-ambient 5) | | 62 | °C/W |
| R ₀ JC | Thermal Resistance Junction-Case | | 3.5 | °C/W |



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------------------------------------|--|---|------|-------|------|-----------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V_{GS} =0 V , I_D =250 u A | 100 | | | V |
| $\triangle BV_{DSS}/\triangle T_{J}$ | BVDSS Temperature Coefficient | Reference to 25 $^{\circ}\mathrm{C}$, ID=1mA | | 0.098 | | V/°C |
| В | Static Drain-Source On-Resistance ² | V_{GS} =10V , I_D =5A | | 50 | 75 | $m\Omega$ |
| R _{DS(ON)} | Static Diain-Source On-Resistance | V_{GS} =4.5 V , I_D =2 A | | 60 | 90 | mΩ |
| $V_{GS(th)}$ | Gate Threshold Voltage | V_{GS} = V_{DS} , I_D =250uA | 1.2 | 2.0 | 2.7 | ٧ |
| | Drain-Source Leakage Current | V_{DS} =80V , V_{GS} =0V , T_{J} =25 $^{\circ}$ C | | | 1 | uA |
| I _{DSS} | | V _{DS} =80V , V _{GS} =0V , T _J =55°C | | | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V_{GS} = $\pm 20V$, V_{DS} = $0V$ | | | ±100 | nA |
| R_g | Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | | 28.8 | | Ω |
| Qg | Total Gate Charge (10V) | V _{GS} =10 V , | | 6.5 | | |
| Q _{gs} | Gate-Source Charge | V _{DS} =50 V, | | 1.4 | | nC |
| Q _{gd} | Gate-Drain Charge | I _D =5 A | | 1.4 | | |
| T _{d(on)} | Turn-On Delay Time | V _{GS} =10 V, | | 14 | | |
| Tr | Rise Time | V _{DS} =50 V, | | 3.2 | | |
| T _{d(off)} | Turn-Off Delay Time | $R_G=2 \Omega$, | | 36 | | ns |
| T _f | Fall Time | I _D =5 A | | 14 | | |
| Ciss | Input Capacitance | V _{GS} =0 V, | | 410 | | |
| C _{oss} | Output Capacitance | V _{DS} =25 V, | | 80 | | pF |
| C _{rss} | Reverse Transfer Capacitance | f=100 KHz | | 50 | | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|-----------------|-------------------------------------|--|------|------|------|------|
| I _S | Continuous diode current1) | \\ -\\ -0\\ Faras Currant | | | 15 | Α |
| I _{SP} | Pulsed diode current ²⁾ | V _G =V _D =0V , Force Current | | | 45 | Α |
| V_{SD} | Diode Forward Voltage ²⁾ | V_{GS} =0V , I_S =5A , T_J =25 $^{\circ}$ C | | | 1.3 | V |
| t _{rr} | Reverse Recovery Time | IF=5A , | | 36 | | nS |
| Q _{rr} | Reverse Recovery Charge | dl/dt=100A/µs , Tյ=25℃ | | 37 | | nC |

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) V_{DD} =50 V, R_G =25 Ω , L=0.3 mH, starting T_j =25 °C.
- 5) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a =25 °C.



Typical Characteristics

C, Capacitance (pF)

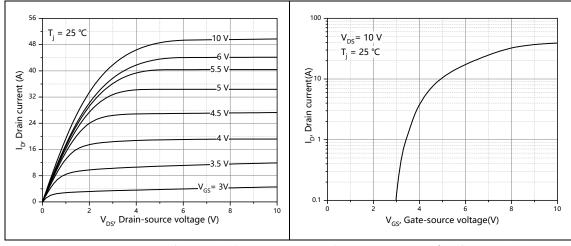


Figure 1, Typ. output characteristics

Figure 2, Typ. transfer characteristics 10³ $I_D = 5 A$ $V_{DS} = 50 \text{ V}$ Gate-source voltage(V) f=100 KHz $V_{GS} = 0 V$ 10⁰ 60 V_{DS}, Drain-source voltage (V) Q_q, Gate charge(nC)

Figure 3, Typ. capacitances

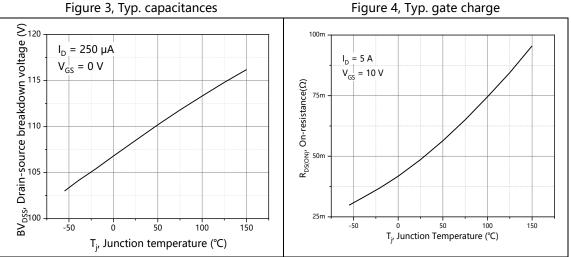


Figure 5, Drain-source breakdown voltage

Figure 6, Drain-source on-state resistance



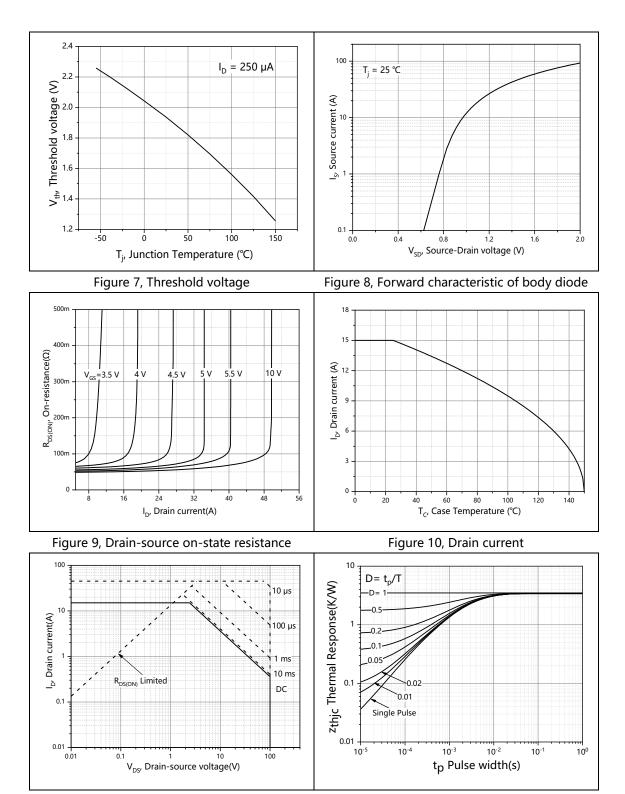
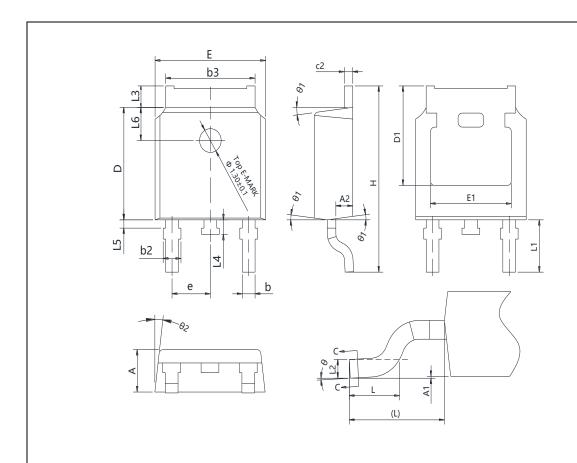


Figure 11, Safe operation area $T_C=25$ °C

Figure 12, Max. transient thermal impedance

TO-252 package outline dimension



| SYMBOL | mm | | | | |
|---------|-------------|-----------|-------|--|--|
| OTMIDOL | MIN | NOM | MAX | | |
| Α | 2.20 | 2.30 | 2.38 | | |
| A1 | 0 | - | 0.10 | | |
| A2 | 0.9 | 1.01 | 0.10 | | |
| b | 0.72 | - | 0.85 | | |
| b1 | 0.71 | 0.76 | 0.81 | | |
| b2 | 0.72 | - | 0.90 | | |
| b3 | 5.13 | 5.33 | 5.46 | | |
| С | 0.47 | - | 0.60 | | |
| c1 | 0.46 | 0.51 | 0.56 | | |
| c2 | 0.47 | - | 0.60 | | |
| D | 6.00 | 6.10 | 6.20 | | |
| D1 | 5.25 | - | • | | |
| E | 6.50 | 6.60 | 6.70 | | |
| E1 | 4.70 | - | • | | |
| е | 2.186 | 2.286 | 2.386 | | |
| Н | 9.80 | 10.10 | 10.40 | | |
| L | 1.40 | 1.50 | 1.70 | | |
| L1 | | 2.90 REF | | | |
| L2 | | 0.508 BSC | | | |
| L3 | 0.90 | - 1.25 | | | |
| L4 | 0.60 | 0.80 | 1.00 | | |
| L5 | 0.15 - 0.75 | | | | |
| L6 | 1.80 REF | | | | |
| θ | 0° | - | 8º | | |
| θ1 | 5° | 7º | 90 | | |
| θ2 | 5° | 7º | 90 | | |



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